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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#13/320-02 Date 2/22/02

In re Application of: Rich Fogal and Michael B. Ball

Serial No.: 09/422,887

Filed: October 21, 1999

For: ANGULARLY OFFSET STACKED DIE MULTICHIP
DEVICE AND METHOD OF MANUFACTURE

§ Group Art Unit: 2822

§ Examiner: J. Brophy

§ Atty. Docket: 95-0134.05

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FORMAL DRAWINGS TRANSMITTAL

Attn: Office of Official Draftsperson/Drawing Review Branch

Commissioner for Patents

Washington, D.C. 20231

Dear Sir:

Certificate of Mailing (37 C.F.R. § 1.8)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date below:

2/19/02 Date

Signature

Applicants herein submit substitute formal drawings in triplicate in addition to a redlined copy. A copy of these drawings have been sent to the Examiner.

Approved
J.B.
6/18/02
2/19/02
Respectfully submitted,

Charles Brantley

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